© Copyrig	al Composition De ght 2005. IPC, Bannockl nal and Pan-American co	ourn, Illinois. A	Ill rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	tion of the encompass	substance es all low	s within the manufactu er level materials for v	urer listed which the	item. Note: manufacture	if the item is an as r has engineering	ssembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distribution								rials and N	ials and Mfg Information				
Supplier Information														
Company name*	Company un	Company unique ID			Unique ID Authority				Respor	Response Date*				
onsemi										2024-04-16				
Contact Name	Title - Conta	Title - Contact			Phone - Contact*				Email	Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com					
Authorized Representative* Tit			Title - Representative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Numb	Requester Item Number Mfr Iter		n Number Mfr Item Name			Effective Da	e Versio	1	Manufacturing Site		Weight*	UOM	Unit Type	
	1SMB59	934BT3G	ZEN SMB REG 3W 24V TR			2024-04-16			VN5		114.91	mg	Each	
Manufacturing Proccess I	Information						-							
Terminal Plating / Grid Array Material Termina		Terminal Base	e Alloy J-STD-020 MSL Rati		L Rating	Peak Pro	Peak Process Body Temperature Ma		are Max Time at Peal	ak Temperature Number of Reflow Cycles		cles		
Matte Tin (Sn) - annealed CU Alloy				1		260		С	30	seco	nds 3			
Comments														
level 1 - maximum time at peak t	temperature during so	Idering is 10-3	0 seconds											
For more information regarding	g material composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	16.81	mg	Supplier	Zinc (Zn)	7440-66-6		0.0202	mg
			Supplier	Iron (Fe)	7439-89-6		0.395	mg
			Supplier	Copper (Cu)	7440-50-8		16.3897	mg
			Supplier	Phosphorus (P)	7723-14-0		0.005	mg
Die	0.7	mg	Supplier	Silicon (Si)	7440-21-3		0.7	mg
Die Attach Solder	0.52	mg	Supplier	Silver (Ag)	7440-22-4		0.013	mg
			А	Lead (Pb)	7439-92-1	7a	0.481	mg
			Supplier	Tin (Sn)	7440-31-5		0.026	mg
Lead Frame	46.99	mg	Supplier	Zinc (Zn)	7440-66-6		0.0564	mg
			Supplier	Iron (Fe)	7439-89-6		1.1043	mg
			Supplier	Copper (Cu)	7440-50-8		45.8153	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0141	mg
Mold Compound-Black	48.07	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.807	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2403	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		6.9701	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		31.2455	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		4.807	mg
Plating	1.82	mg	Supplier	Tin (Sn)	7440-31-5		1.82	mg